

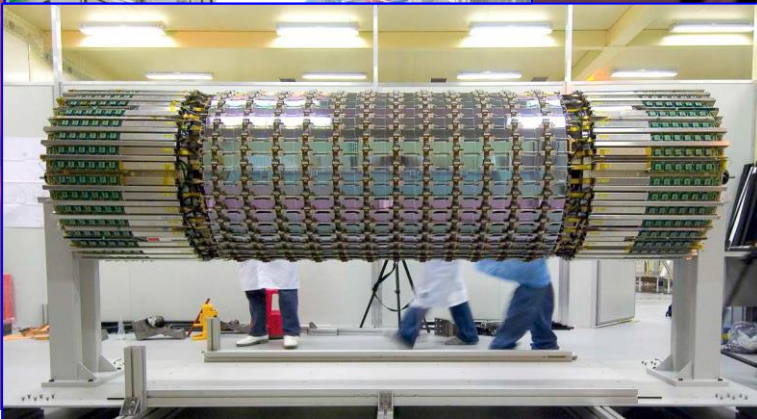
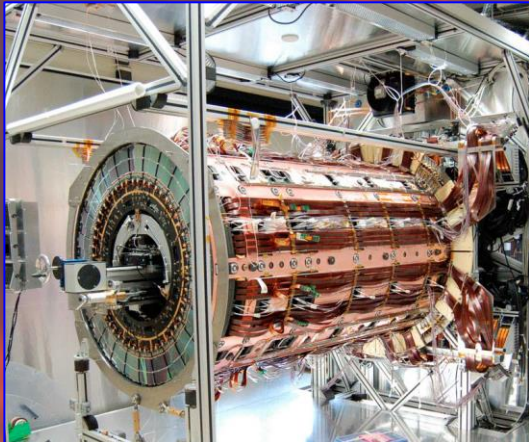
# The Operation and Performance of the ATLAS Semi-Conductor Tracker in the 3 years covering 2010-2012 LS1 Activities, Lessons learned

**Steve McMahon**

**RAL**

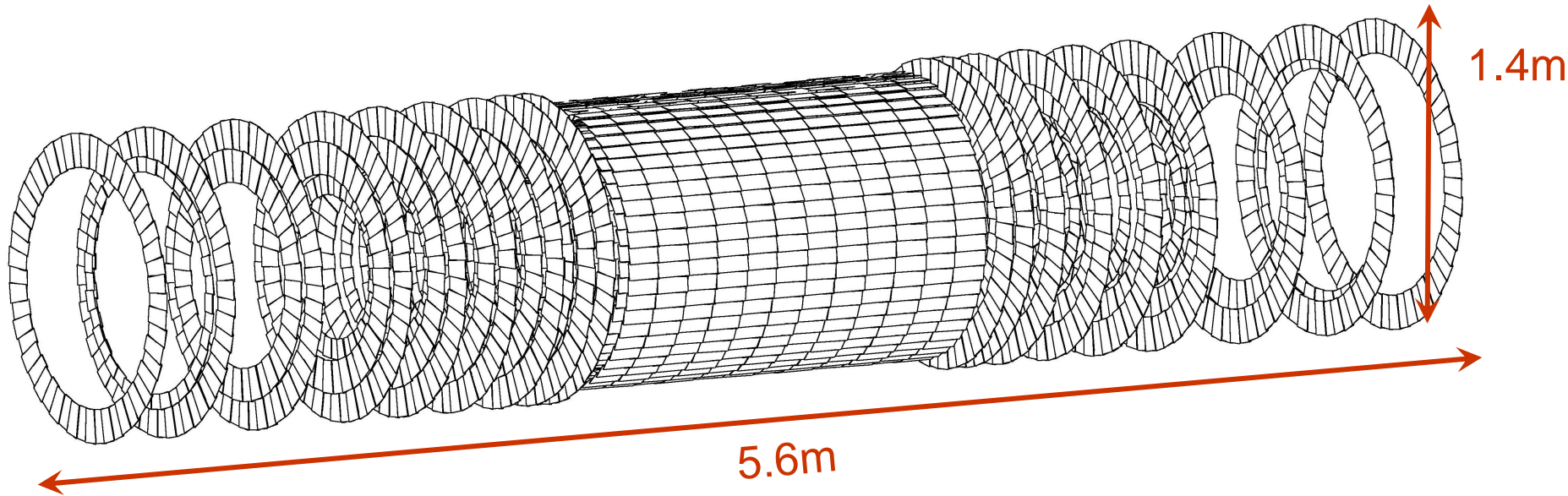
**on behalf of the SCT**

**HSTD9-Hiroshima : 5<sup>th</sup> September 2013**



# The Semi Conductor Tracker (SCT)

- 61 m<sup>2</sup> of silicon with 6.2 million readout channels
- 4088 silicon modules in 4 Barrels and 18 Disks (9 each end) :  $|\eta| < 2.5$
- 30cm < R < 52cm, space point resolution  $r\phi \sim 16\mu\text{m}$  /  $R \sim 580\mu\text{m}$
- Designed for 700fb<sup>-1</sup> integrated luminosity



- C<sub>3</sub>F<sub>8</sub> Cooling (-7°C to +4.5°C silicon) to limit radiation damage
- Radiation hard: tested to 2x10<sup>14</sup> 1-MeV neutron equivalent/cm<sup>2</sup>
- Lightweight: 3% X0 per layer

# The SCT Sensor Details

## General

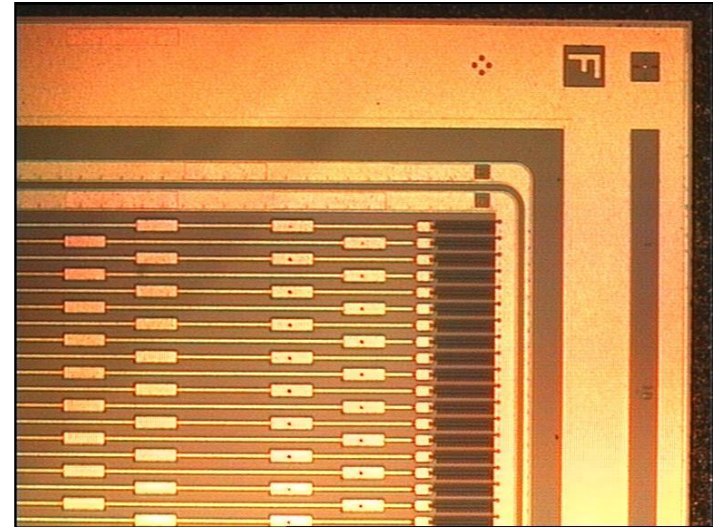
- Single sided p-in-n
- 285  $\mu\text{m}$  thick
- 768 (6x128) + 2 : AC-coupled strips

## SCT:Barrel

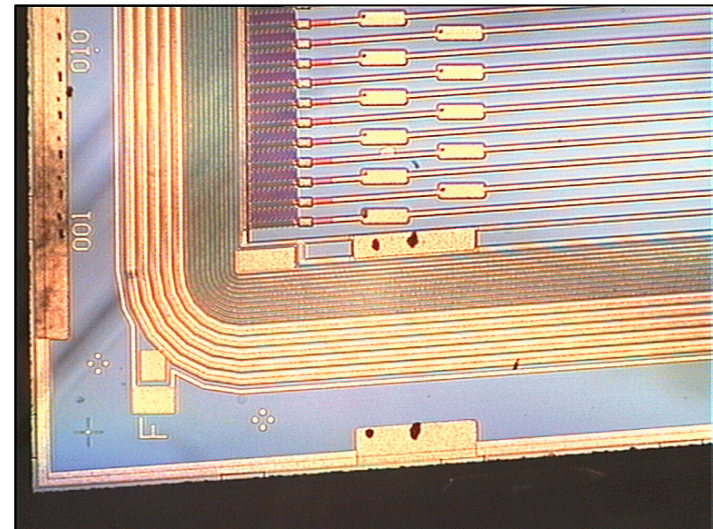
- 8448 sensors
- 8081 sensors with  $\langle 111 \rangle$
- 367 sensors with  $\langle 100 \rangle$
- 64.0 x 63.6mm
- 80 $\mu\text{m}$  strip pitch
- 100% supplied by Hamamatsu

## SCT:End-Cap

- 6944  $\langle 111 \rangle$  wedge sensors
- 56.9 - 90.4 $\mu\text{m}$  strip pitch
- 5 “wedge types”
- 82.8% Hamamatsu
- 17.2% CiS (some oxygenated)

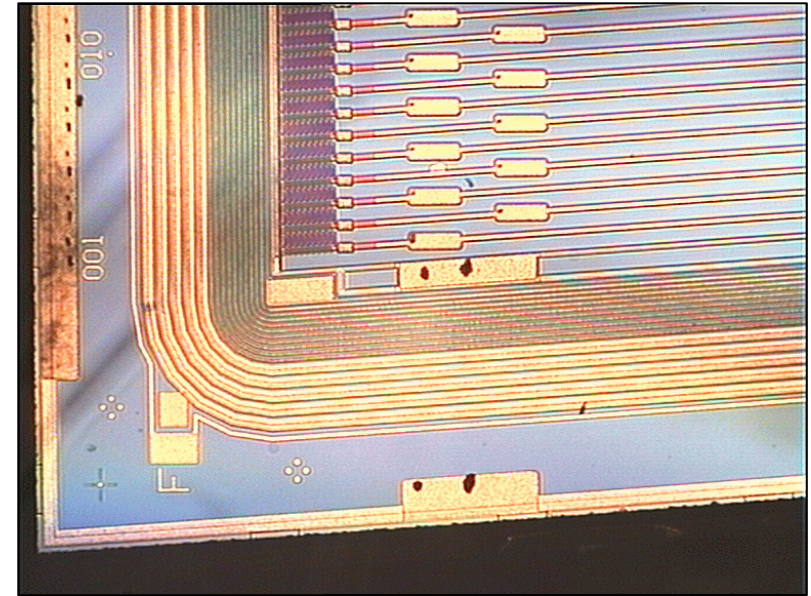
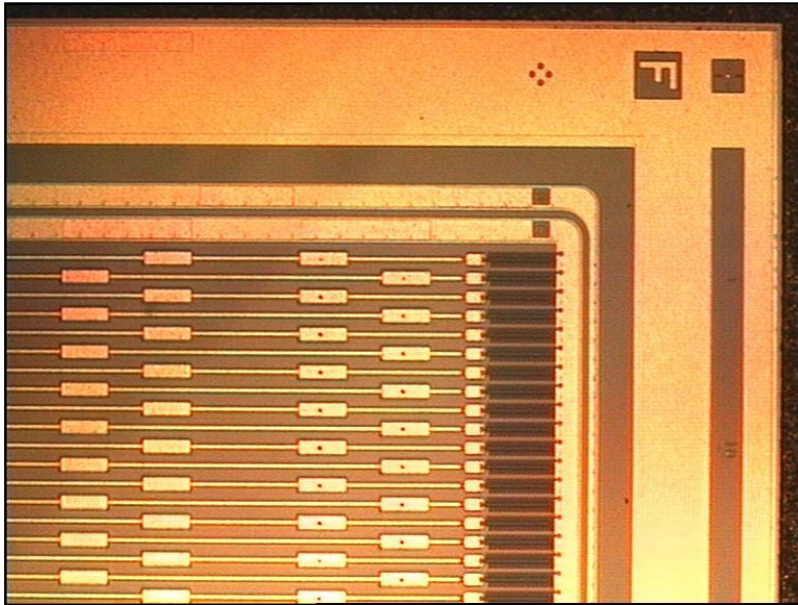


HPK-Barrel



CiS End-Cap

# “Same specification, different species”



**Bias Resistors (1.5M $\Omega$ )**

**Strip metal/implant widths ( $\mu\text{m}$ )**

**Guard design**

**HPK (left)**

**Polysilicon**

**20/16**

**Single floating**

**CiS**

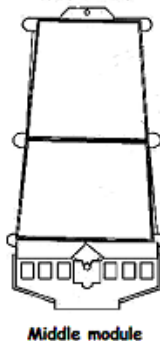
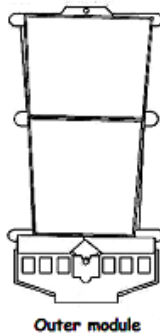
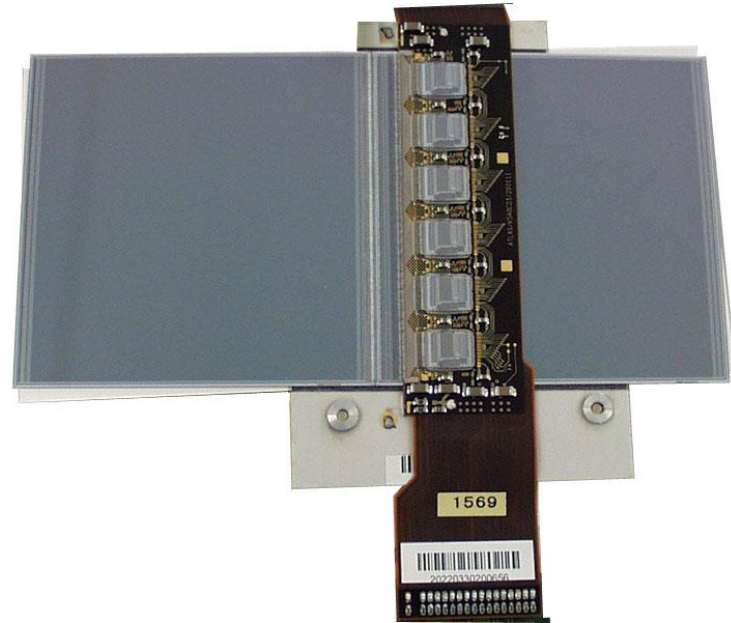
**Implant**

**16/20**

**Multi-guard**

# The SCT Modules

- Back-to-back sensors, glued to highly thermal conductive substrates for mechanical/thermal stability, wire-bonded to form ~12cm long strips
- 40 mrad stereo angle between strips on opposite sides
- 1536 channels (768 on each side)
- 5.6W/module (rising to ~9W after 10 yrs LHC)
- up to 500V sensor bias (nominal 150V)
- Readout by 12 rad-hard ASICs (binary hit-no-hit)



- 2112 barrel modules
  - one shape
  - 1976 end-cap modules
  - 3 shapes
- ←
- Each module has its own HV and LV supply
  - Multiple modules on single cooling loop

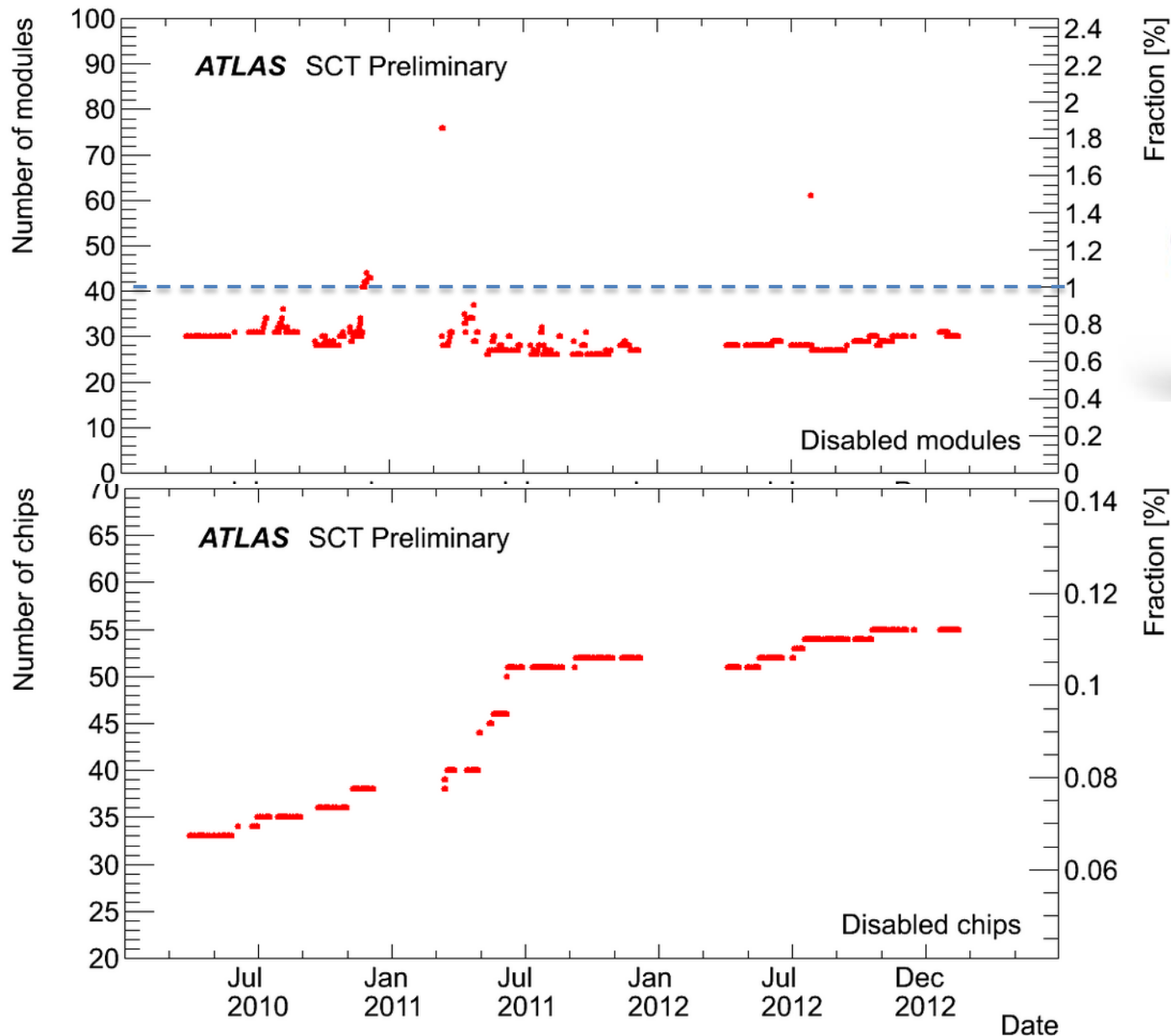
# SCT Detector Configuration

**How many of the: modules, chips and strips are in the standard physics configuration and how stable are these numbers over time?**

**We put a lot of effort into operational stability and high up time.**

# Evolution of the Detector Configuration

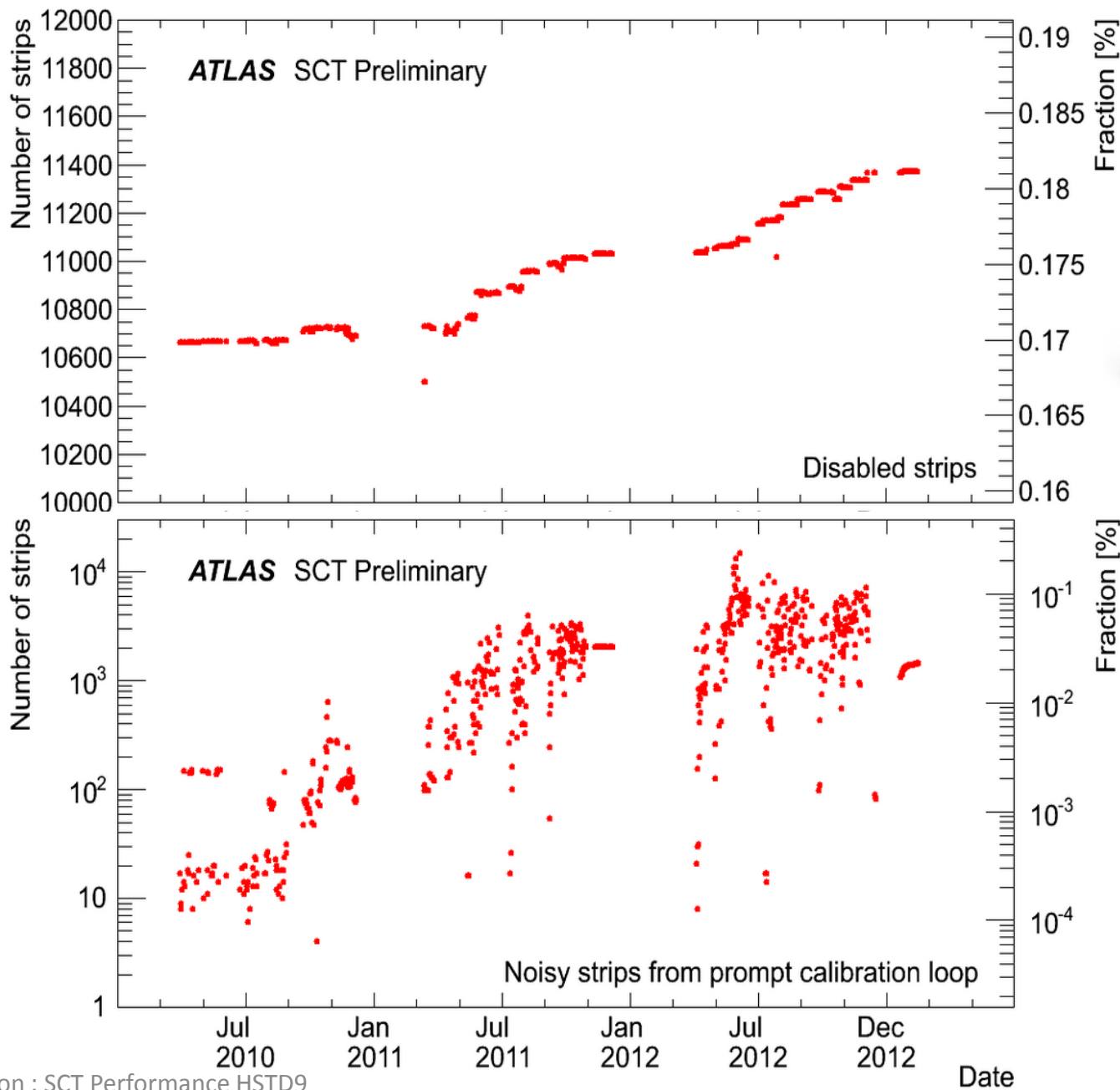
Chips (49,056) Modules (4088)



Note the scale

# Evolution of the Detector Configuration - 2

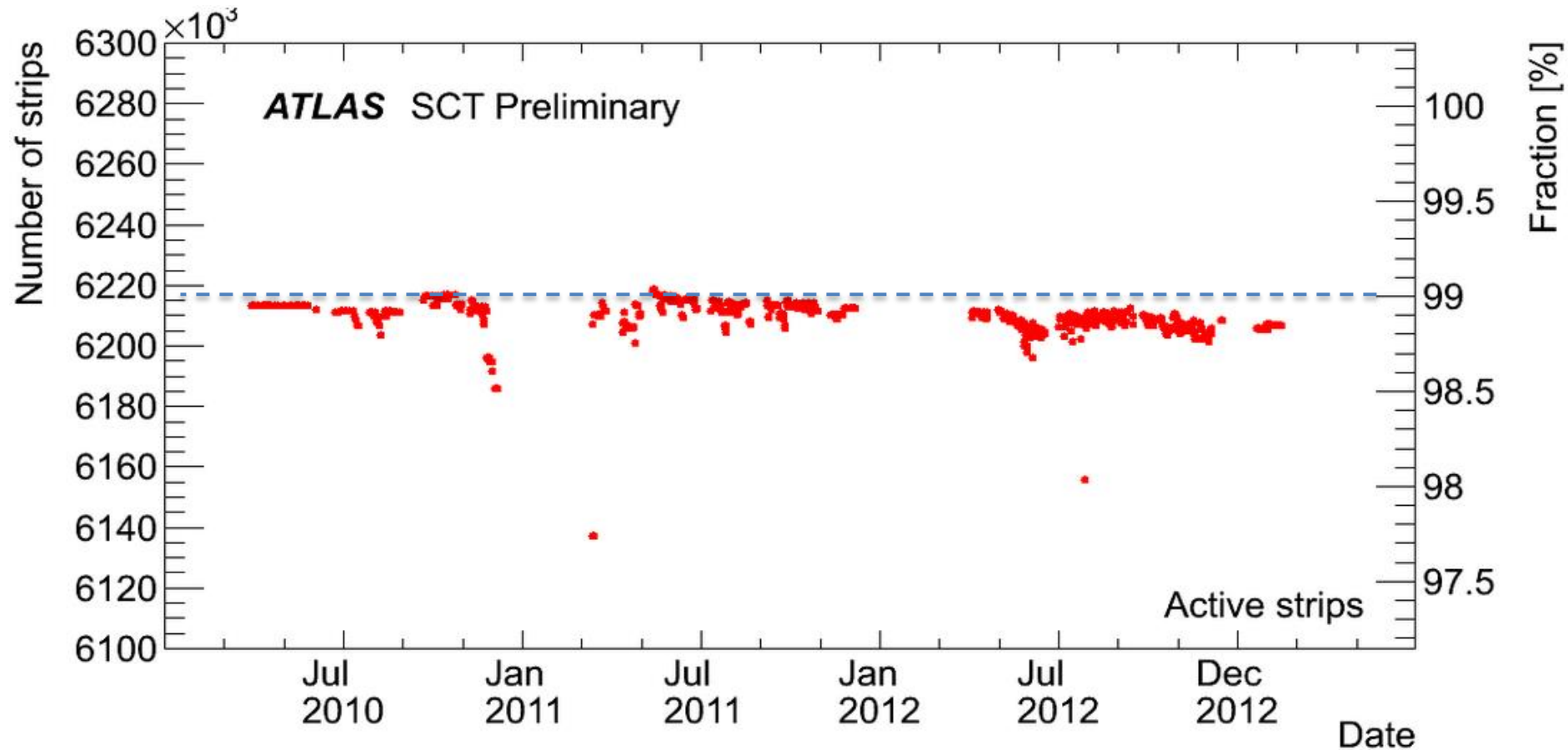
Strips Dead and Noisy (6.3M)



Note the scale



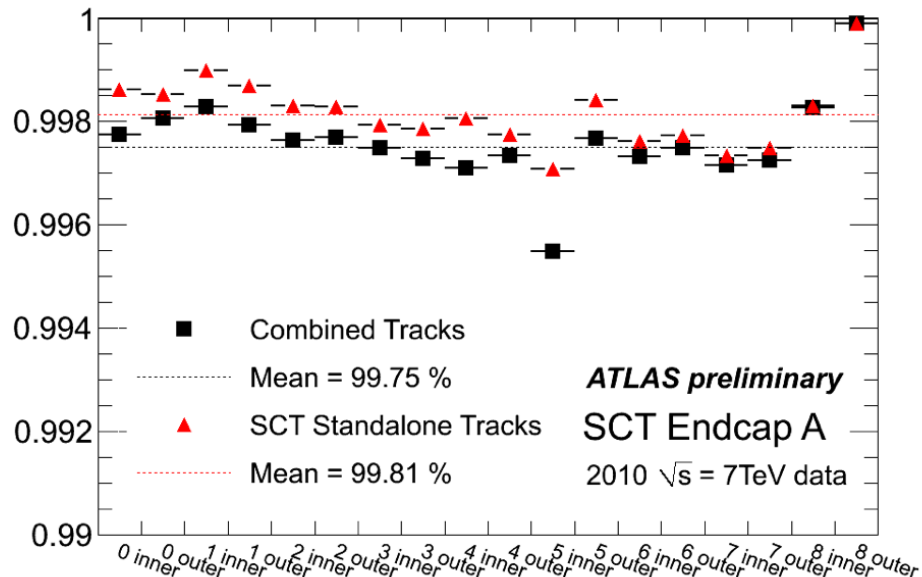
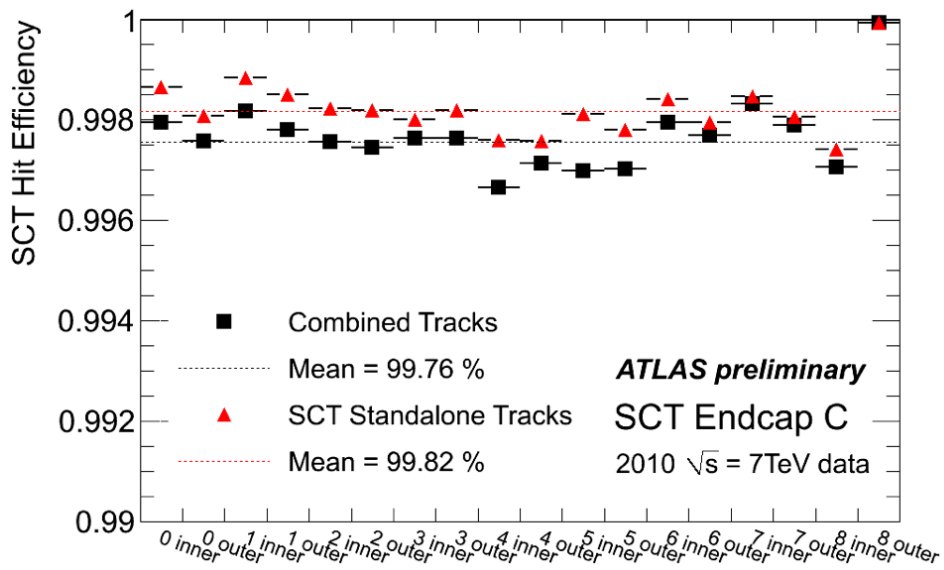
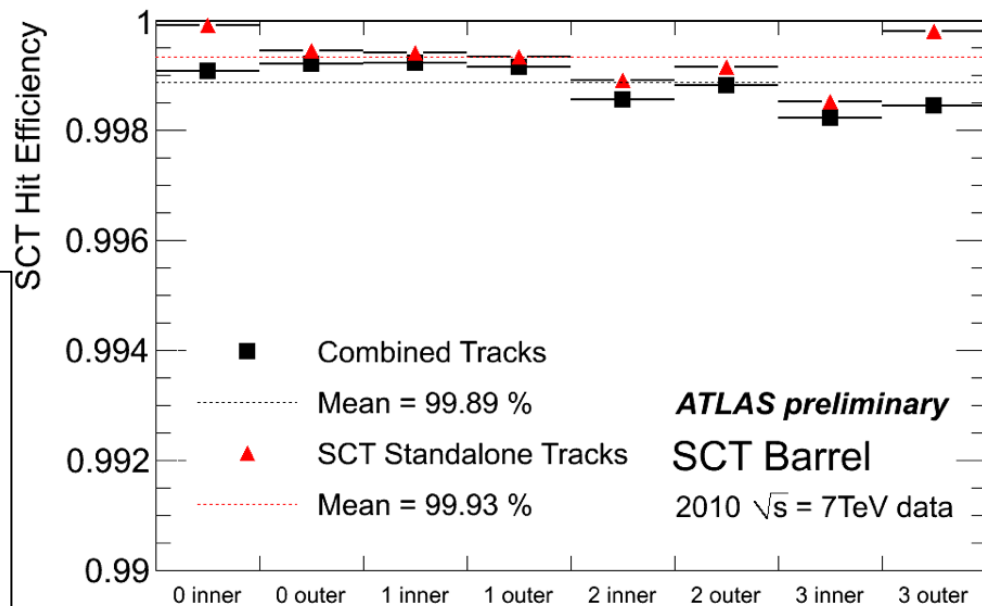
# Number/Fraction of strips in the bulk event reconstruction : total 6.3M



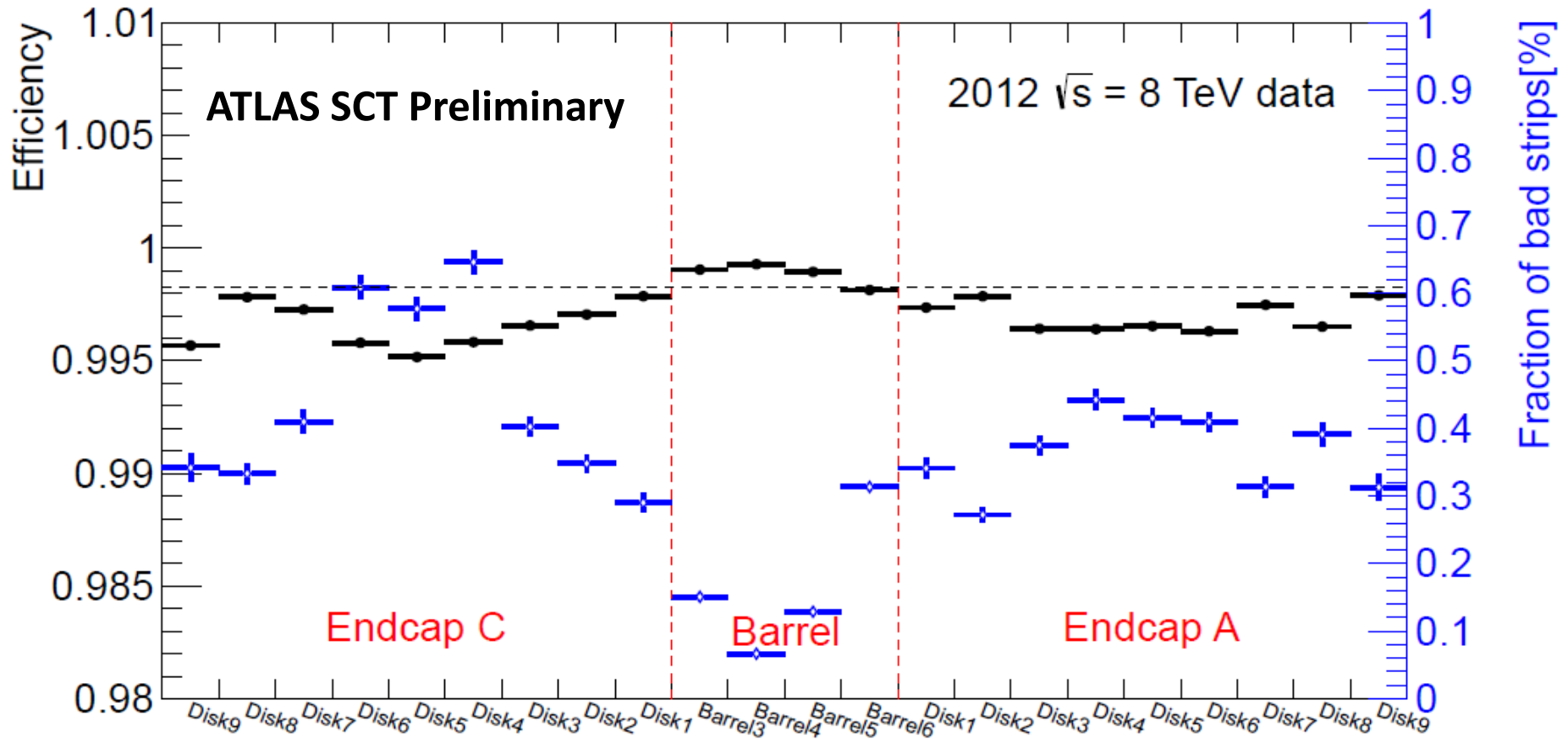
**Without removing the masked noisy-strips we are above 99% throughout the 3 years**

# Intrinsic Hit Efficiency

- #Hits/#Possible hits on tracks
- Takes account of missing modules/chips
- Require  $P_T > 1\text{GeV}/c$
- Require  $\geq 7$  hits for SCT standalone
- Require  $\geq 6$  hits for ID combined



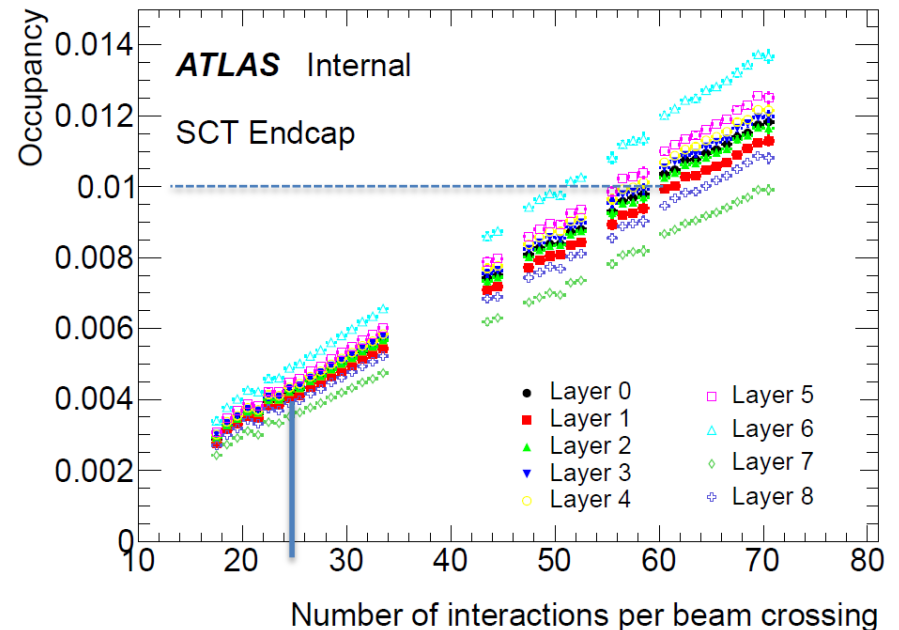
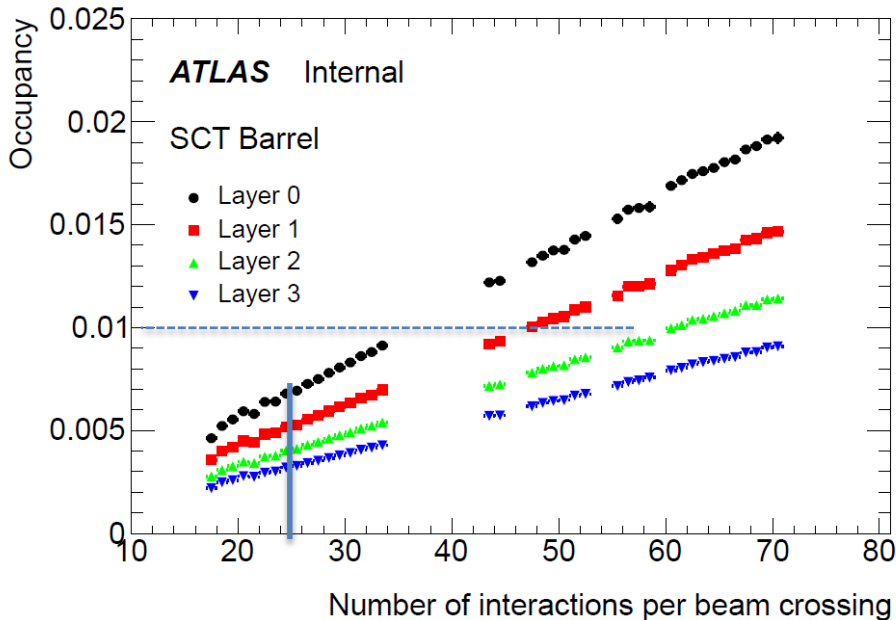
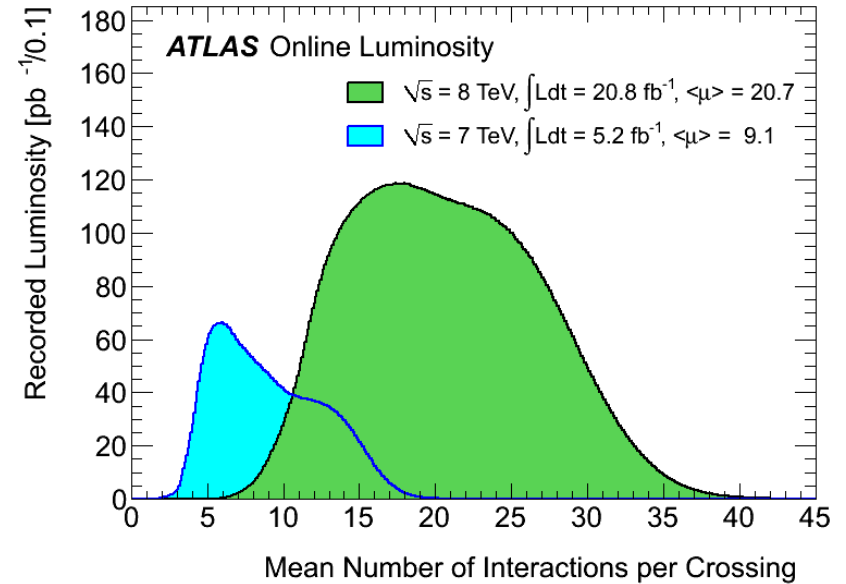
# SCT single Hit Efficiency



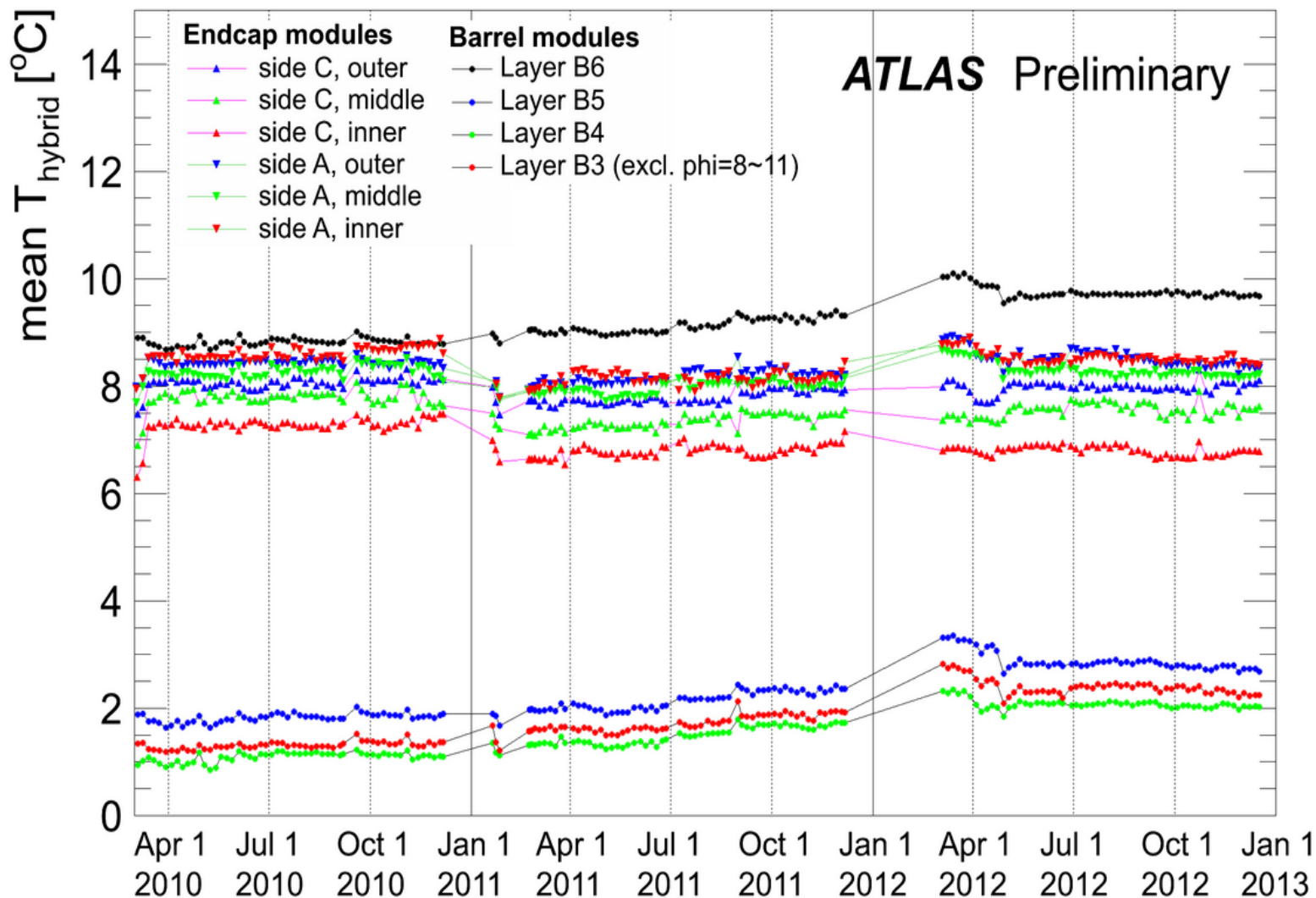
Taken from a special run in 2012 with a low number of p-p interactions per crossing

# SCT Strip Occupancies

Detector occupancies for different parts of the SCT as a function of the number of interactions per proton-proton crossing  
 Note the SCT was designed for 1% occ at 25ns

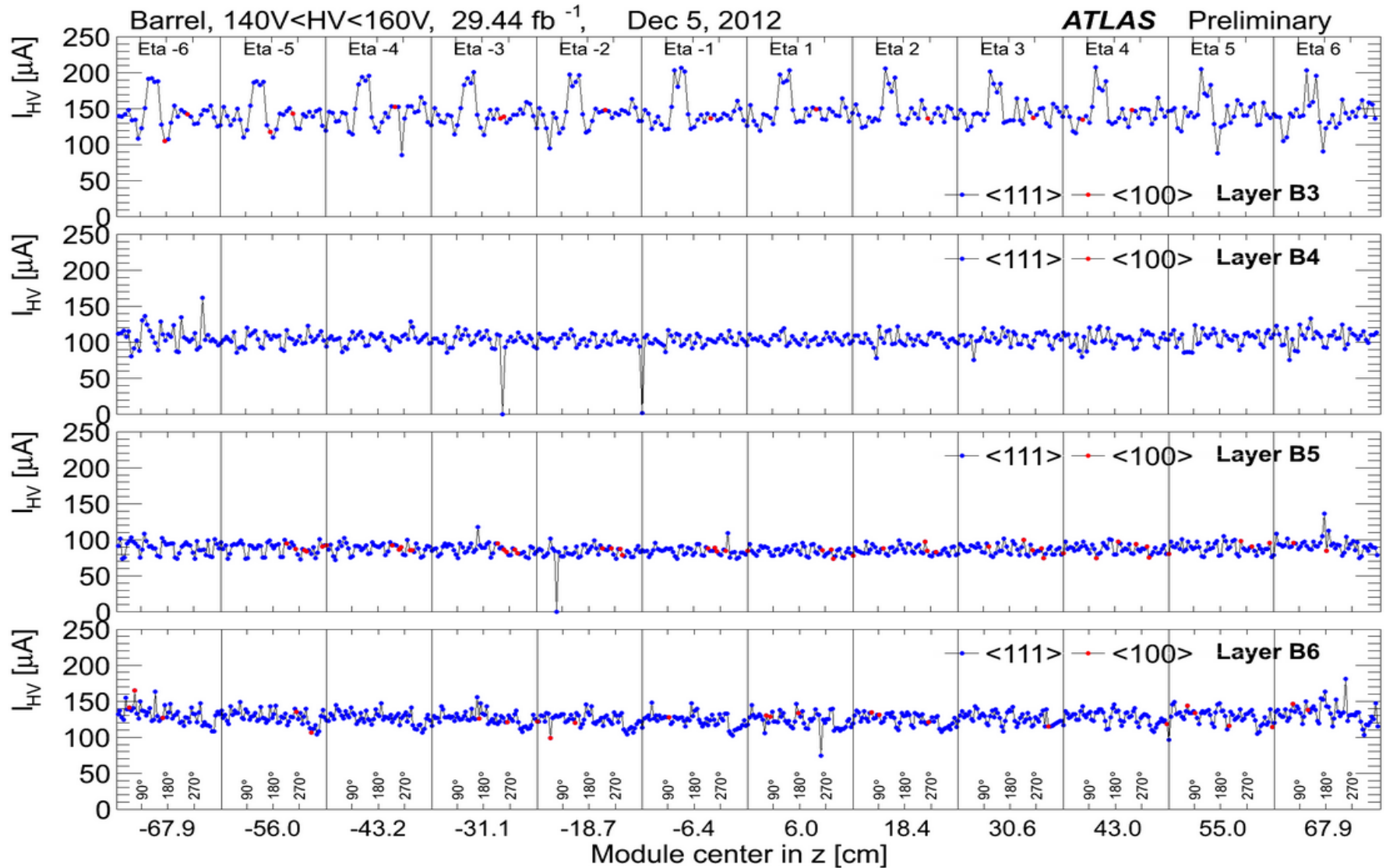


# Temperature Stability



Important to understand the evolution of the temperature of the sensors to understand radiation damage.  
Note these results are a direct measurements of the hybrid temperature  
Note we also need to understand the  $dT$  between hybrid and the surface of the sensor.

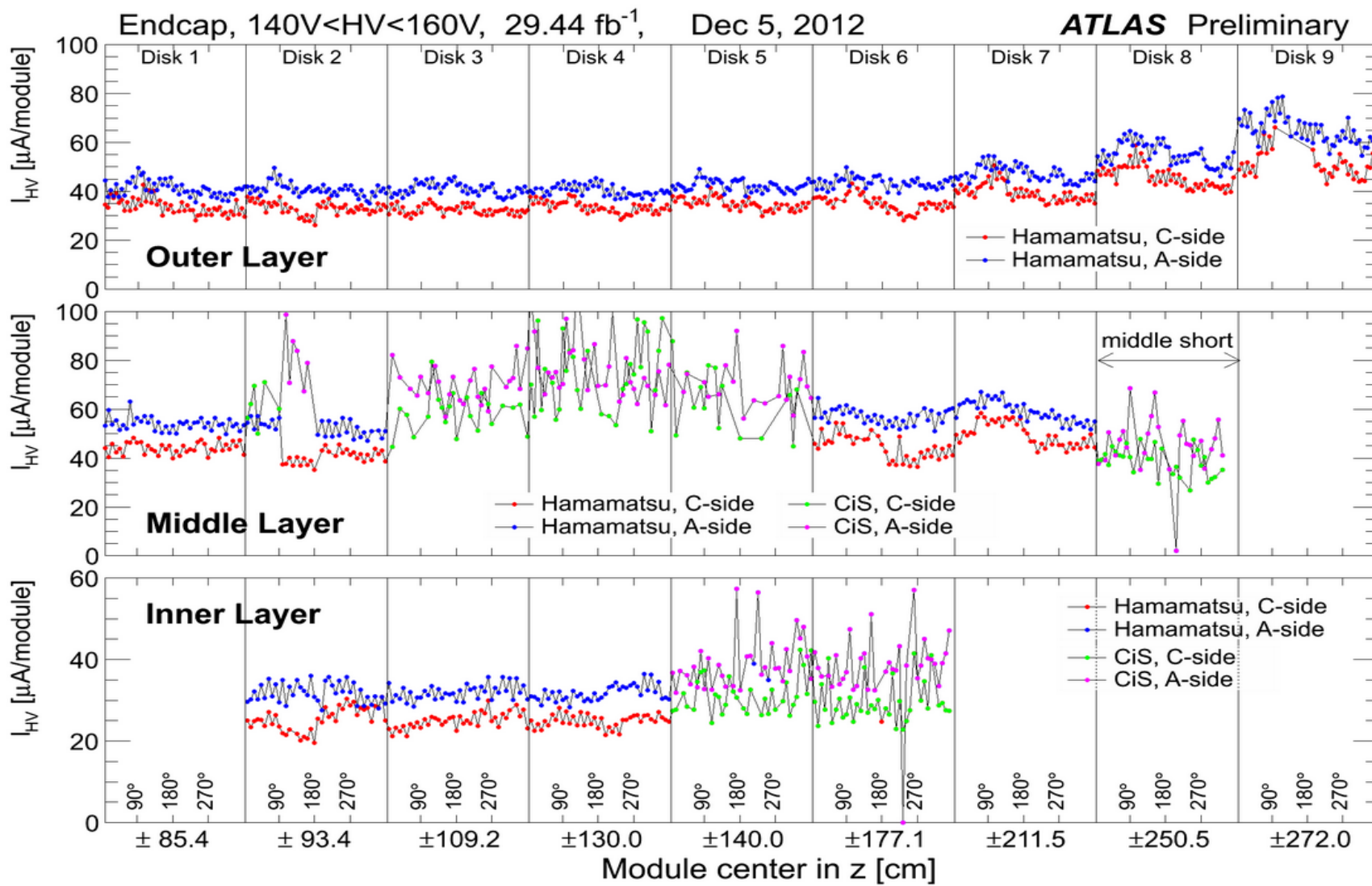
# SCT Leakage currents in the Barrels



Snapshot taken in December 2012

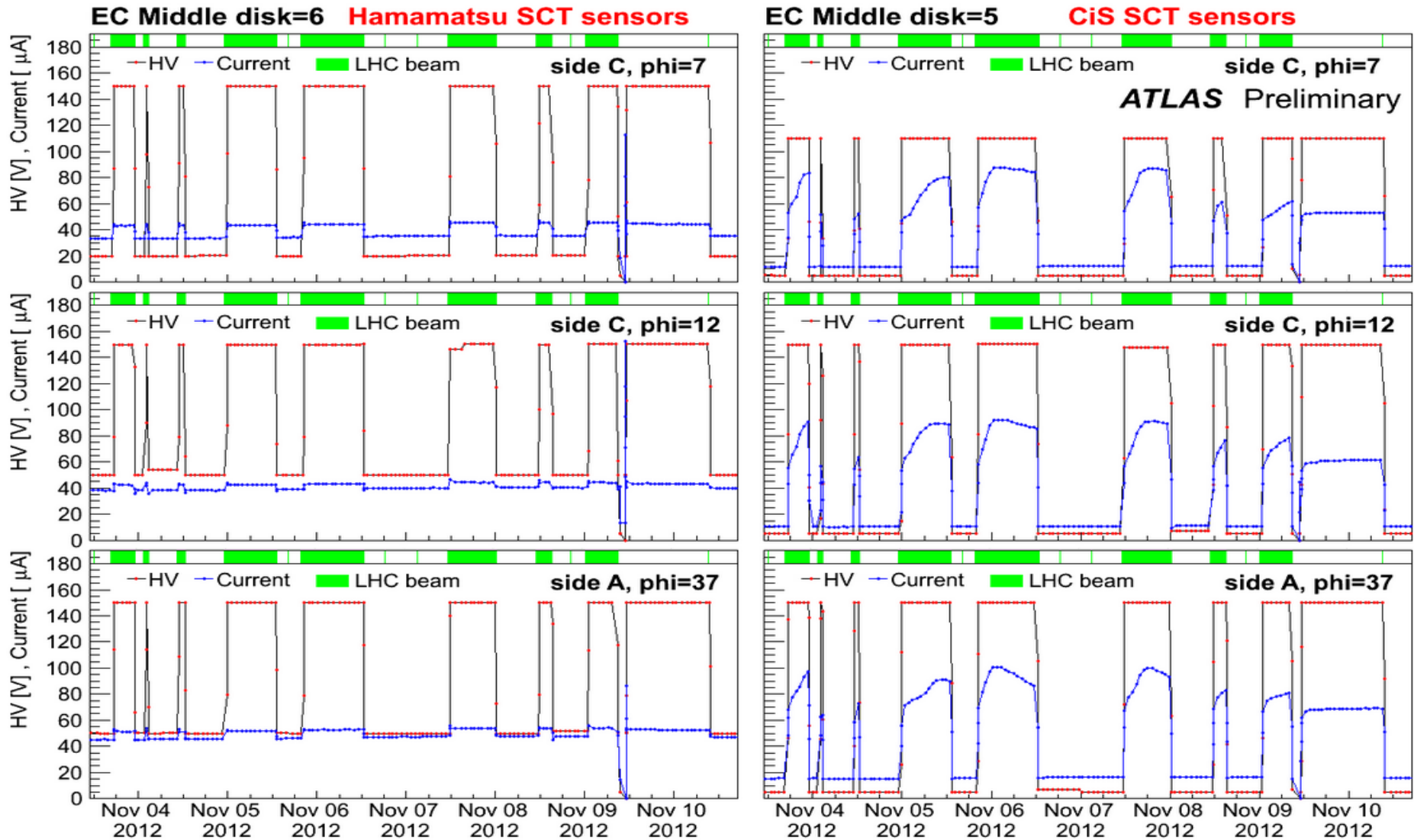
Note that these values are the “raw” (unscaled) values

# SCT Leakage currents in the End-Caps



Snapshot taken in December 2012

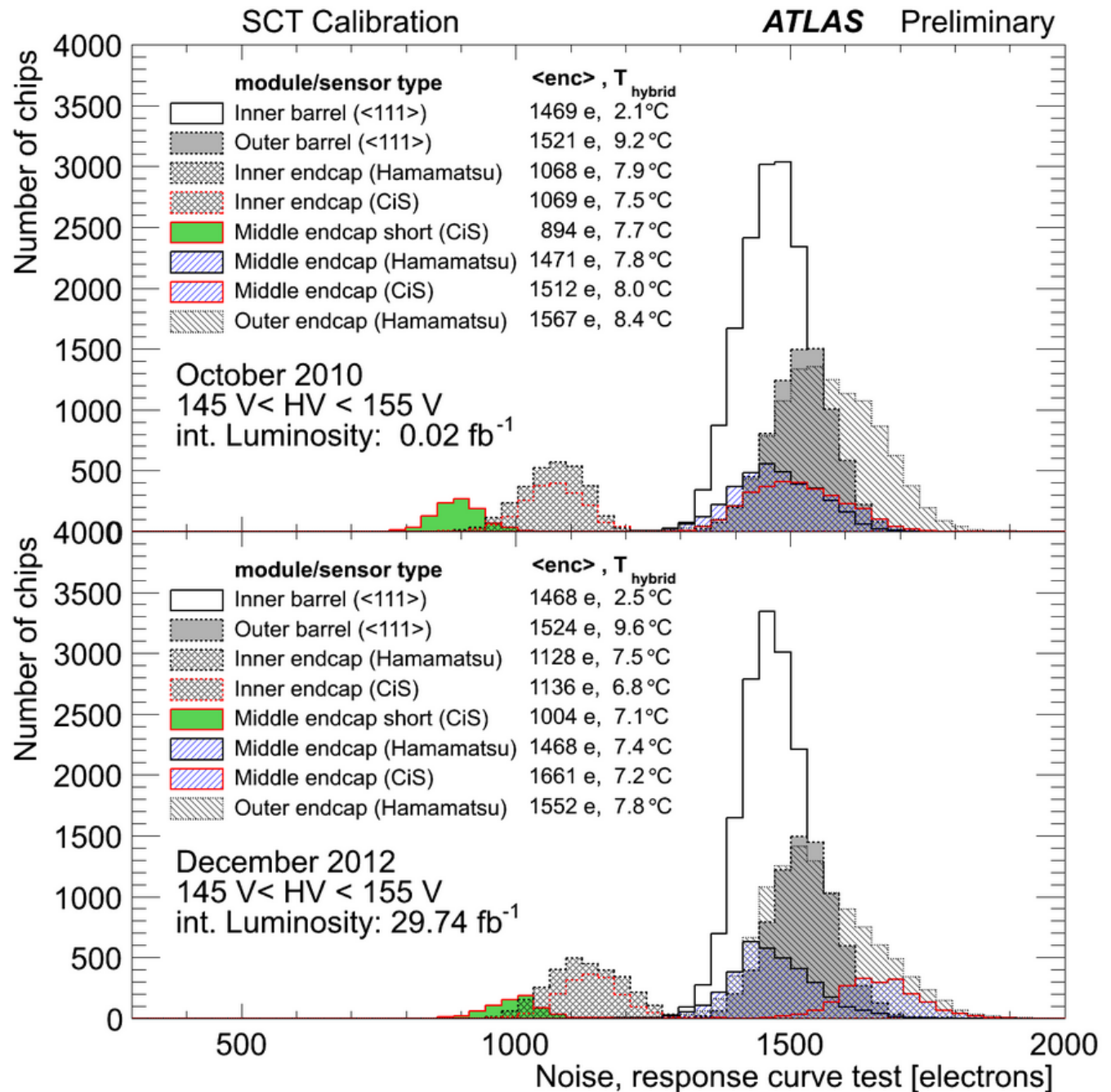
# Current in the End-Caps : HPK & CiS



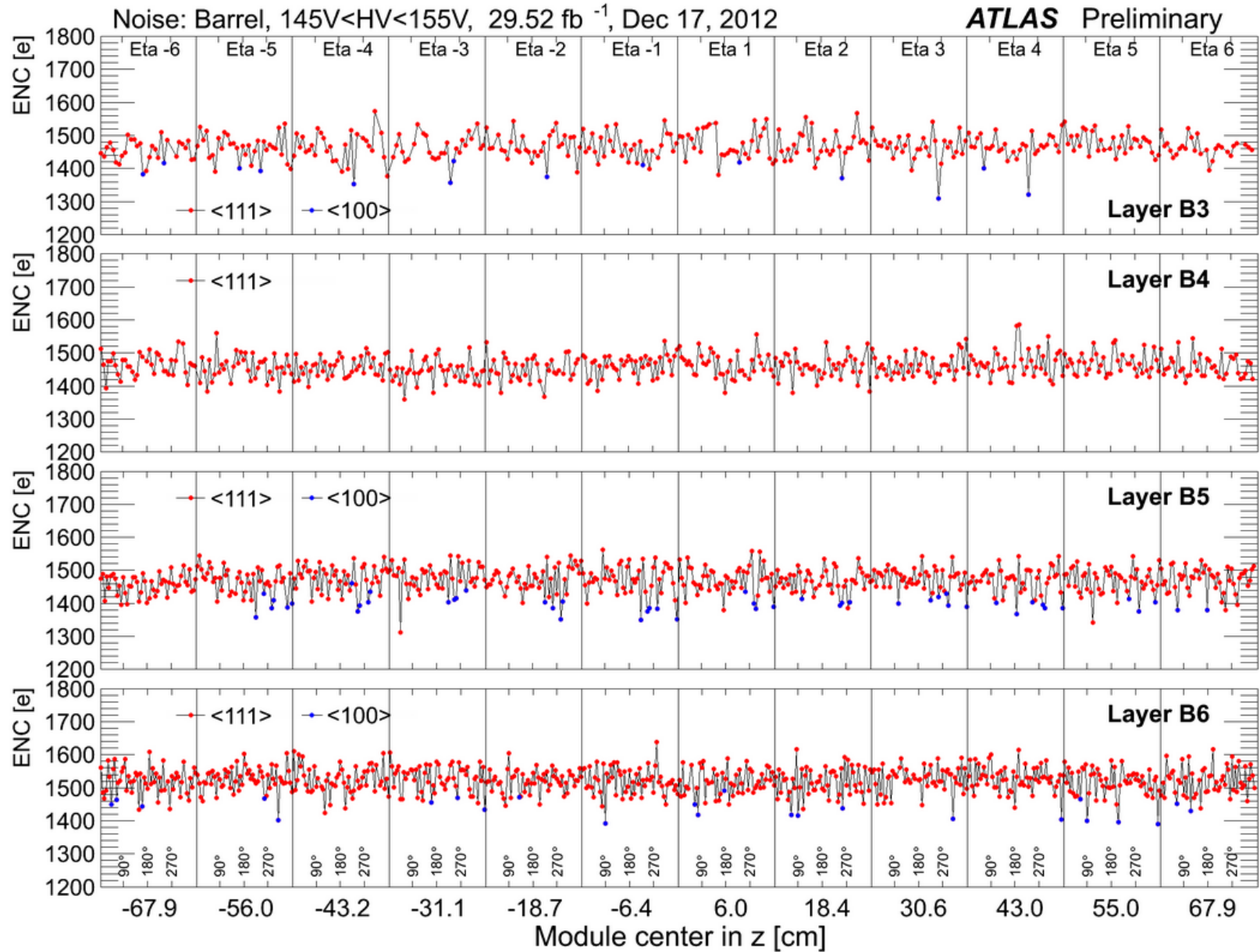
Snapshot taken in 2012 : Shows the Voltage and Current histories for individual modules



# ENC Noise (2010 – 2012)

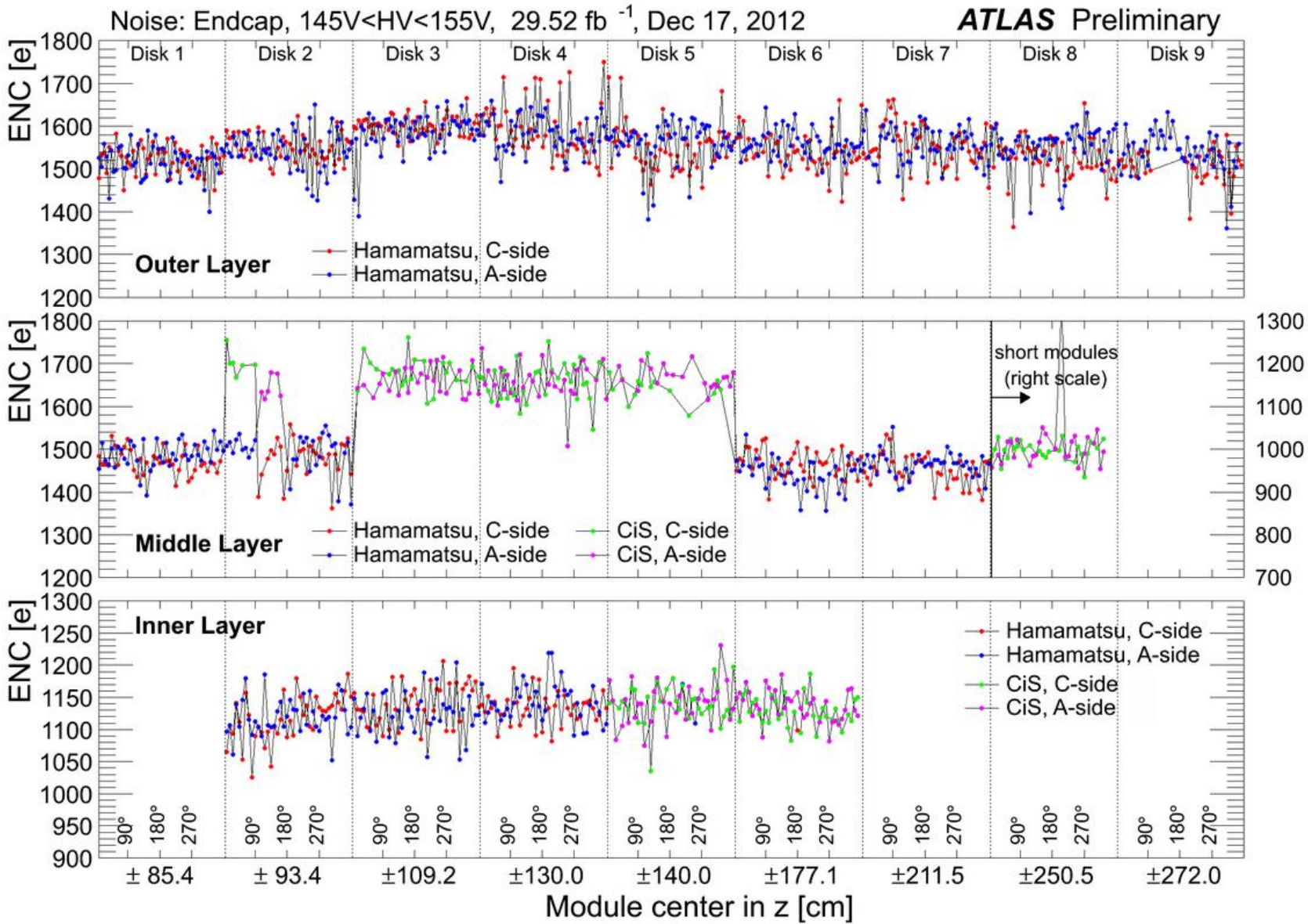


# ENC Noise in the Barrel



Snapshot taken in December 2012

# ENC Noise in the End-Caps

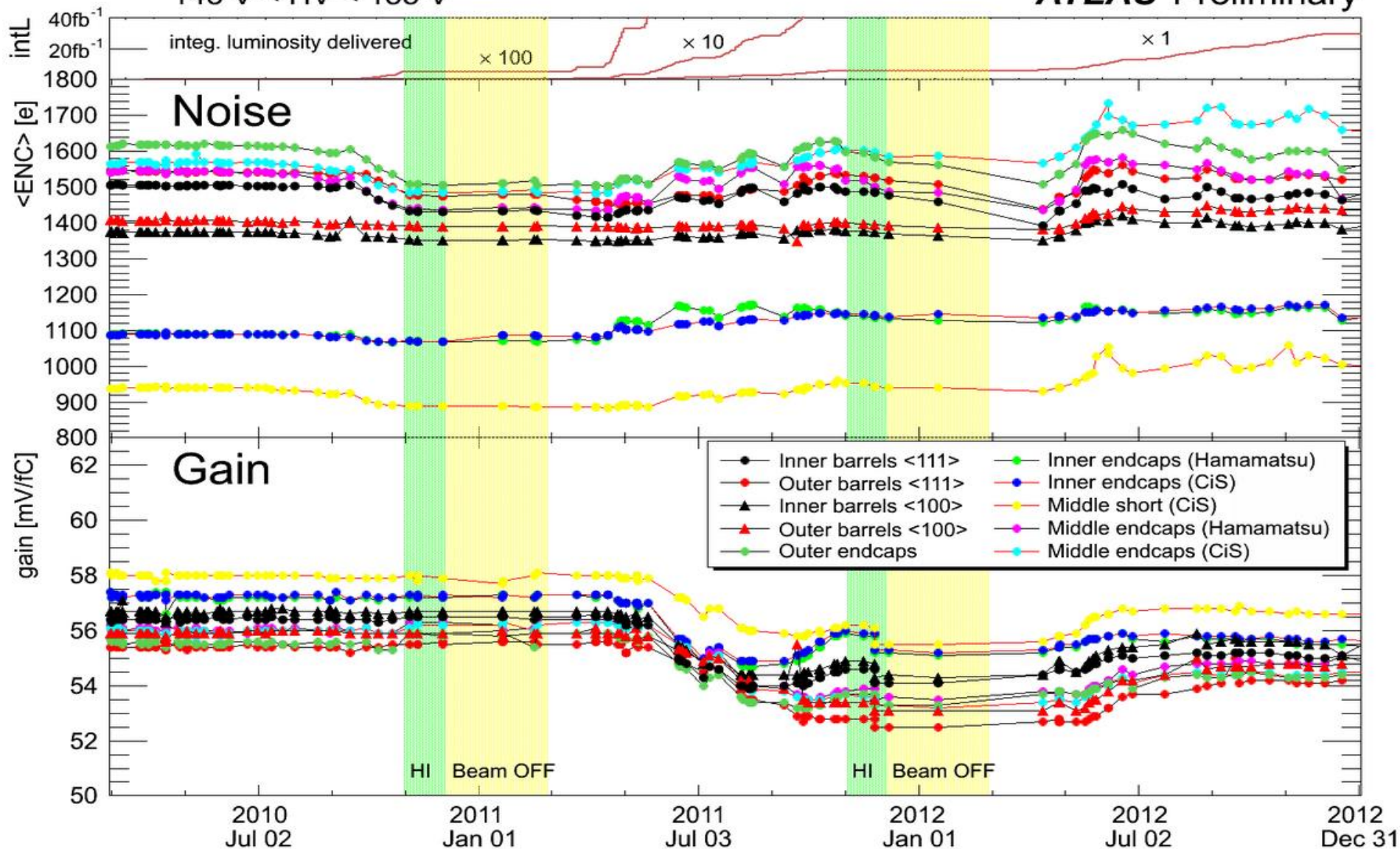


Snapshot taken in December 2012

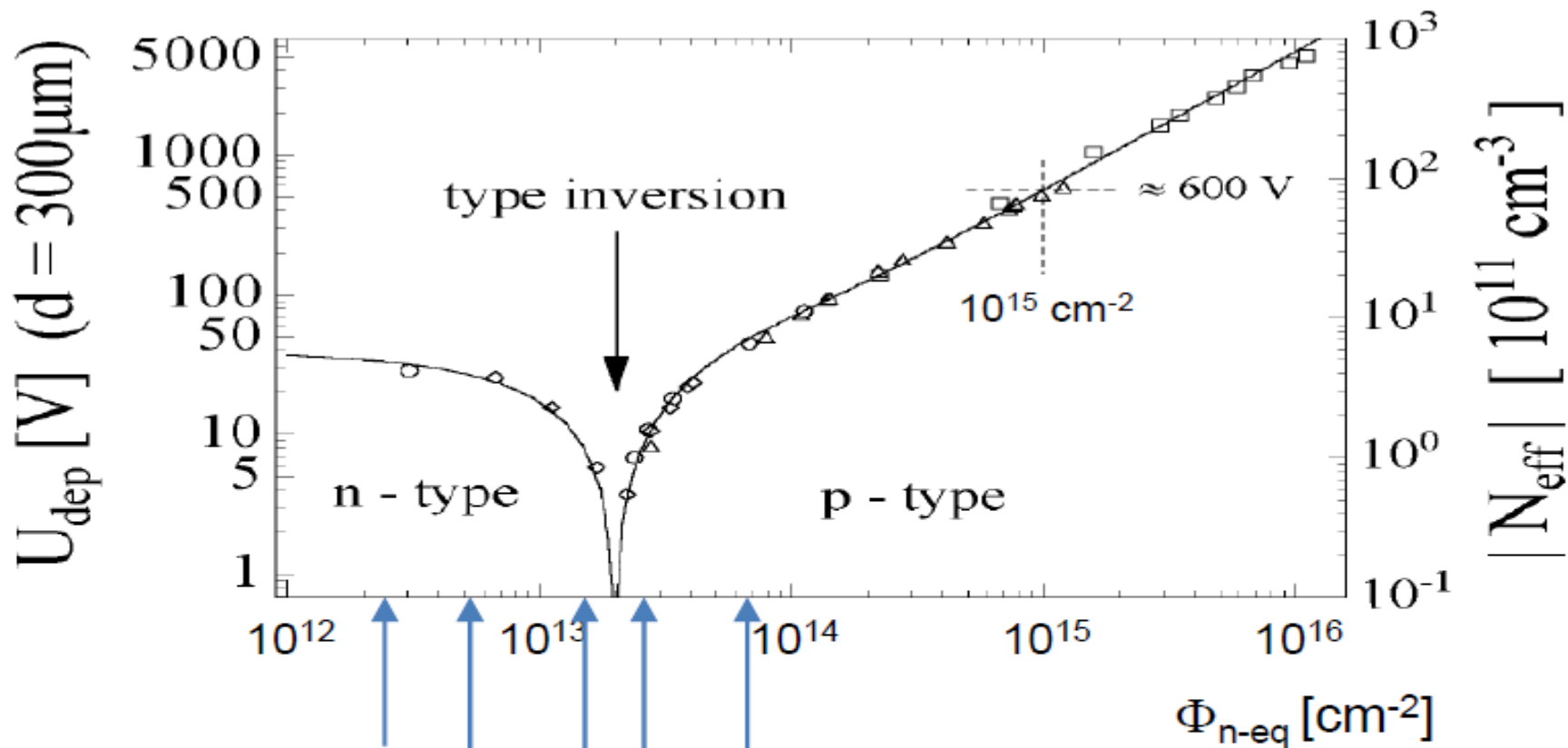
# Time Evolution of Noise & Gain : B & EC

145 V < HV < 155 V

ATLAS Preliminary



## Expected Radiation Dose and Depletion Voltage Shift – Status as of End 2012



For HPK initial  
Vd = 60-80V

B6:  $2.8 \times 10^{12}$

**SCT**

B3:  $5.1 \times 10^{12}$

B2:  $1.7 \times 10^{13}$

**Pixel**

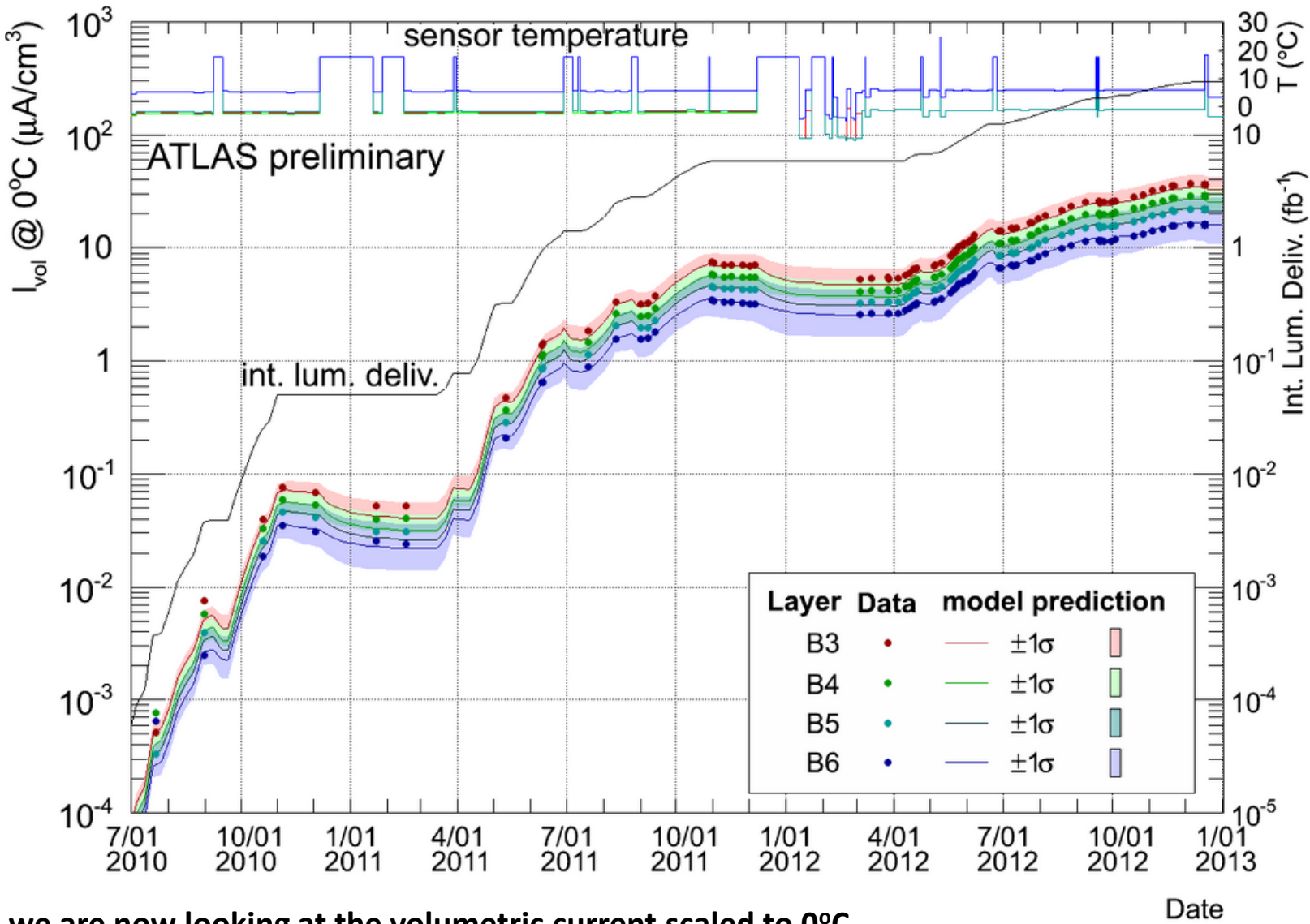
B1:  $2.7 \times 10^{13}$

B0:  $6.6 \times 10^{13}$

**1 MeV n-eq fluence  
received**

**Integrated luminosity delivered =  
5.8 (7 TeV) + 23.8 (8 TeV)  $\text{fb}^{-1}$   
+ using the Fluka simulation**

# Evolution of Leakage current in SCT Barrels compared to a prediction



**Note we are now looking at the volumetric current scaled to 0°C**  
**Fluka used to convert luminosity to flux of 1MeV neutron-equivalent**  
**Effective band gap = 1.21eV (see A. Chilingarov RD50 Technical note RD-50-2011-1)**

# LS1 Activities (2013-2015)

- **SCT power and cooling were switched off in February 2013.**
  - The SCT will remain warm throughout most of LS1
  - Cooling and powering of SCT is expected to return in [Mid 2014](#)
- **Numerous SCT consolidation activities**
  1. Upgrade/expansion of SCT-DAQ
    - Installation of an additional 38 Read-Out Drivers (RODs)
    - These will remove a critical DAQ bottleneck and will allow us to be able to read out the SCT up to  $3 \times 10^{34} \text{ cm}^{-2} \text{ s}^{-1} \text{ u}$  (assuming 25ns bunch spacing)
    - Installation of new TX optical engines in the Back Of Crate (BOC) cards
  2. Commissioning of new Thermosiphon cooling system
    - See following slide and diagram in back up.
  3. Testing/repair of evaporative heaters

# Cooling : Why the Thermosiphon?

- Although the compressor based cooling system has been very reliable up to the end of 2012, the compressors themselves are problematic and need extensive support by a team of engineers & technicians
  - Concerns about long term reliability
  - Filter changes (clogging)
- Thermosiphon offers several significant advantages:
  - Cleanliness (no moving parts)
  - Fewer connections
  - Accessibility (interventions possible without interruption to cooling)
  - Reliability
- Commissioning of new system foreseen for Summer 2014
  - Initially with bypass (dummy load), then SCT
  - Compressor system will remain operational as a backup



# Problems and some Lessons Learned

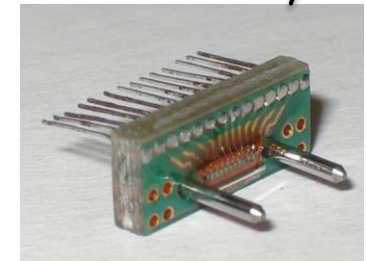
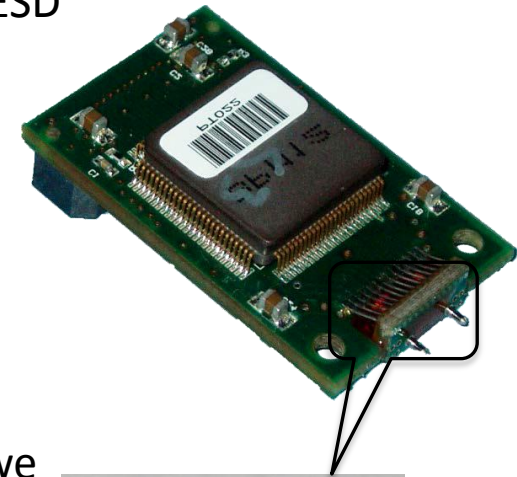
**There were some problems along the way: The commissioning of the evaporative cooling system was problematic, small failures on the thermal management between sub-detector. One big headache were the TXs. I will focus on the last one and try and draw some conclusions for the future.**

# SCT Optical communication General

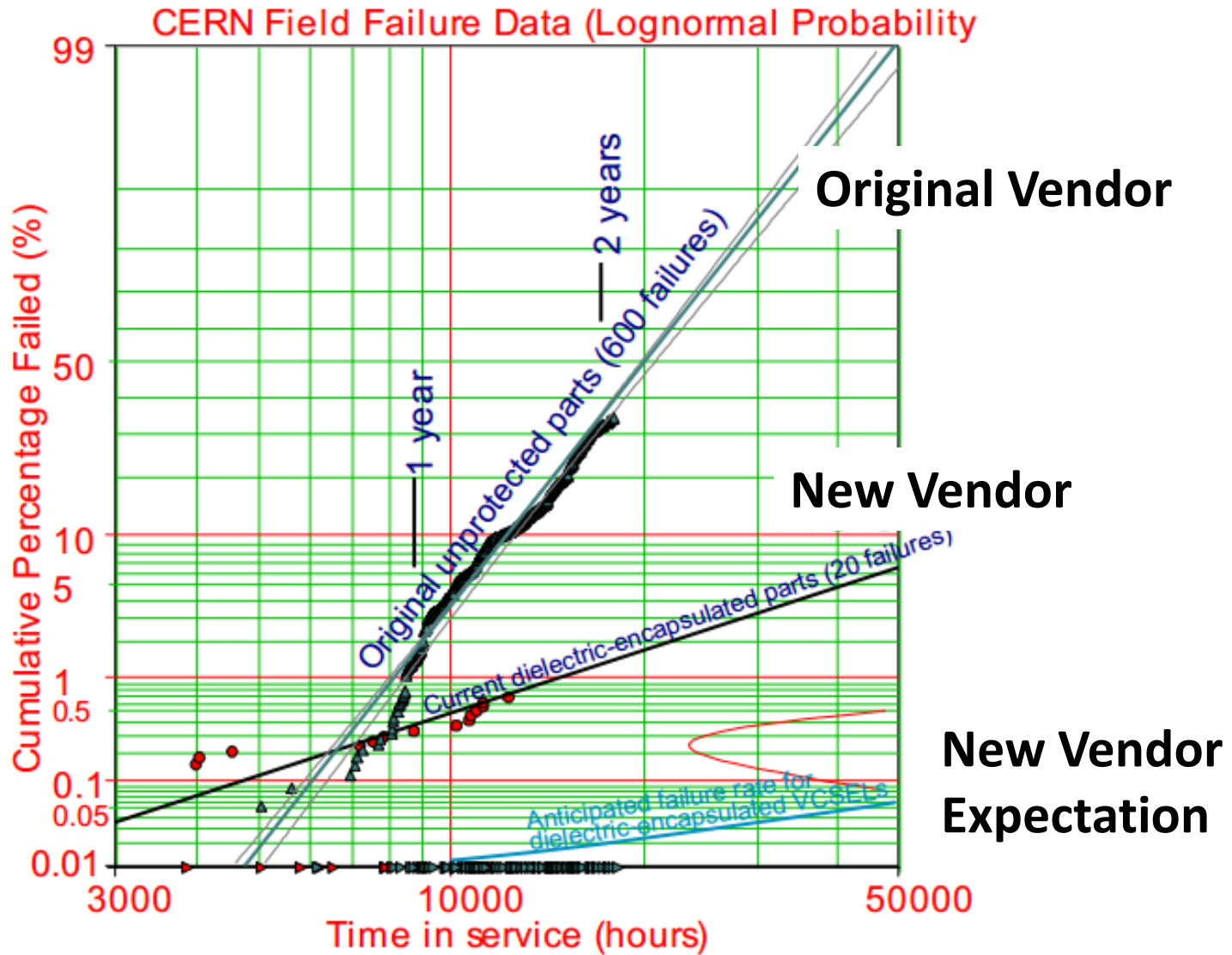
- Two way optical communication between the module and readout.
- Each module is served by **3 optical fibres**.
  - **2 Fibres** (one on each side serving 6 chips) take the data from the module to the readout electronics (RODs) in the counting room.
  - The transmission is done by VCSELs. The VCSEL technology is proton implant (now redundant)
  - **1 Fibre** takes the clock and control from the counting room to the module.
  - The transmission is done by VCSELs. The technology is oxide confinement.
  - The VCSELs are commercial, the packaging is custom, in-house. There is nothing particularly complex about the packaging..

# The off detector TX problem(s)

- **First batch of VCSELs failed**
  - Failure rate at peak ~2 arrays/day (each arrays serves 12 modules)
  - Rolling replacement policy, no significant loss of physics data
  - Identified ESD precautions as a weak point and ensured strict ESD controls for new production
- **Second batch also failed ...**
  - Identified ingress of humidity as an issue
  - replaced all VCSELs with humidity resistant VCSEL from a new vendor
- **Third batch also “failed” ...**
  - Much much lower rate of failures but still factors above what we were expecting based on vendors reliability data.
    - Failure rates in bench tests were incompatible with rates measured in the counting rooms
    - ***humidity not the full story.***
- Still trying to understand all causes of failures (not purely academic ..)
- Now focussing on developments using commercial VCSEL packages



# SCT - VCSEL Failure Rates



# Conclusions

- The SCT has had an outstanding 3 years and has contributed to the rich and diverse program of ATLAS physics.
- We have installed, commissioned and maintained a fantastic strip detector with accumulated channel failures at the 1% level. We also have a very high efficiency, data taking efficiency (>99%).
- We have put great emphasis on configuration stability reliability and up time during operations.
- The effects of radiation damage (*increase in leakage currents*) are entirely consistent with our expectations (Hamburg/Dortmund model) based on our knowledge of the: integrated flux and sensors temperature without any need for scaling or tuning.
- We are currently consolidating the detector during the first long shut-down of the LHC to improve the cooling system and expand the DAQ system to be able to cope with 3 times the design luminosity.
- We have had a few problems which we have circumvented and are using the lessons learned in our planning for the next generation of large scale tracking detector. Reliability will be a big issue in the future....

# Backup Slides

# Breakdown of Physics Configuration

	Endcaps	Barrel	SCT	Fraction (%)
<b>Total</b>	<b>19</b>	<b>11</b>	<b>30</b>	<b>0.73</b>
<b>Cooling</b>	<b>13</b>	<b>0</b>	<b>13</b>	<b>0.32</b>
<b>LV</b>	<b>1</b>	<b>6</b>	<b>7</b>	<b>0.17</b>
<b>HV</b>	<b>5</b>	<b>1</b>	<b>6</b>	<b>0.15</b>
<b>Readout</b>	<b>1</b>	<b>4</b>	<b>4</b>	<b>0.09</b>

Component	Endcaps	Barrel	SCT	Fraction (%)
<b>Modules</b>	<b>20</b>	<b>11</b>	<b>30</b>	<b>0.73</b>
<b>Chips</b>	<b>17</b>	<b>38</b>	<b>55</b>	<b>0.11</b>
<b>Strips</b>	<b>7252</b>	<b>4111</b>	<b>11363</b>	<b>0.18</b>

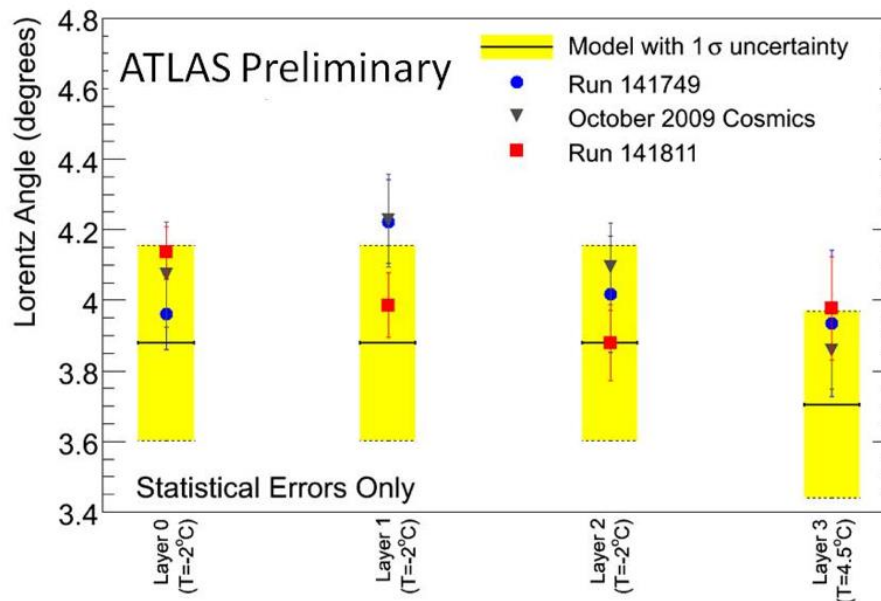
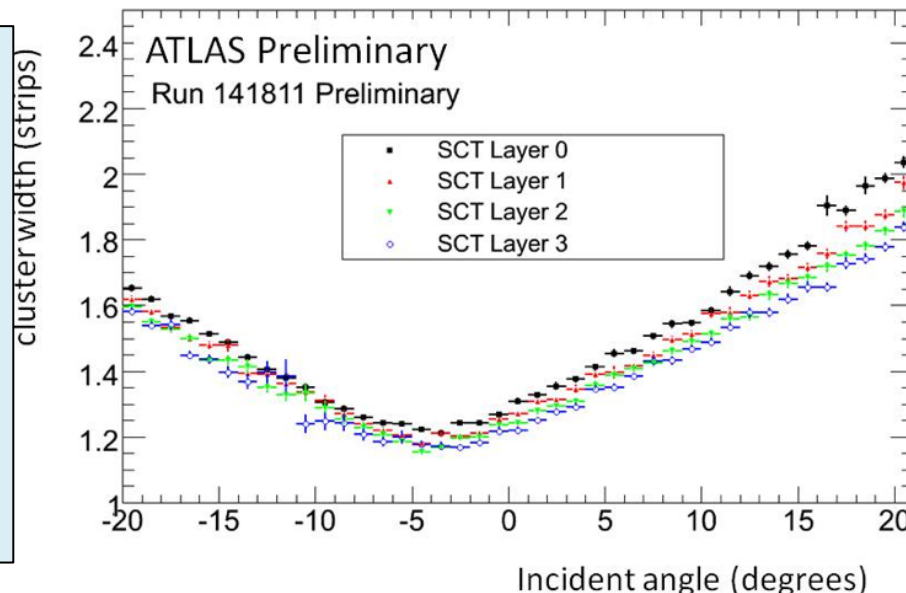
# Lorentz Angle

- Carrier drift direction is deflected in B-field
- Lorentz angle - track incidence angle at which the minimum cluster size (#hits in cluster) is detected
- Lorentz angle is function of B-field, voltage and temperature

Prediction sensitive to:

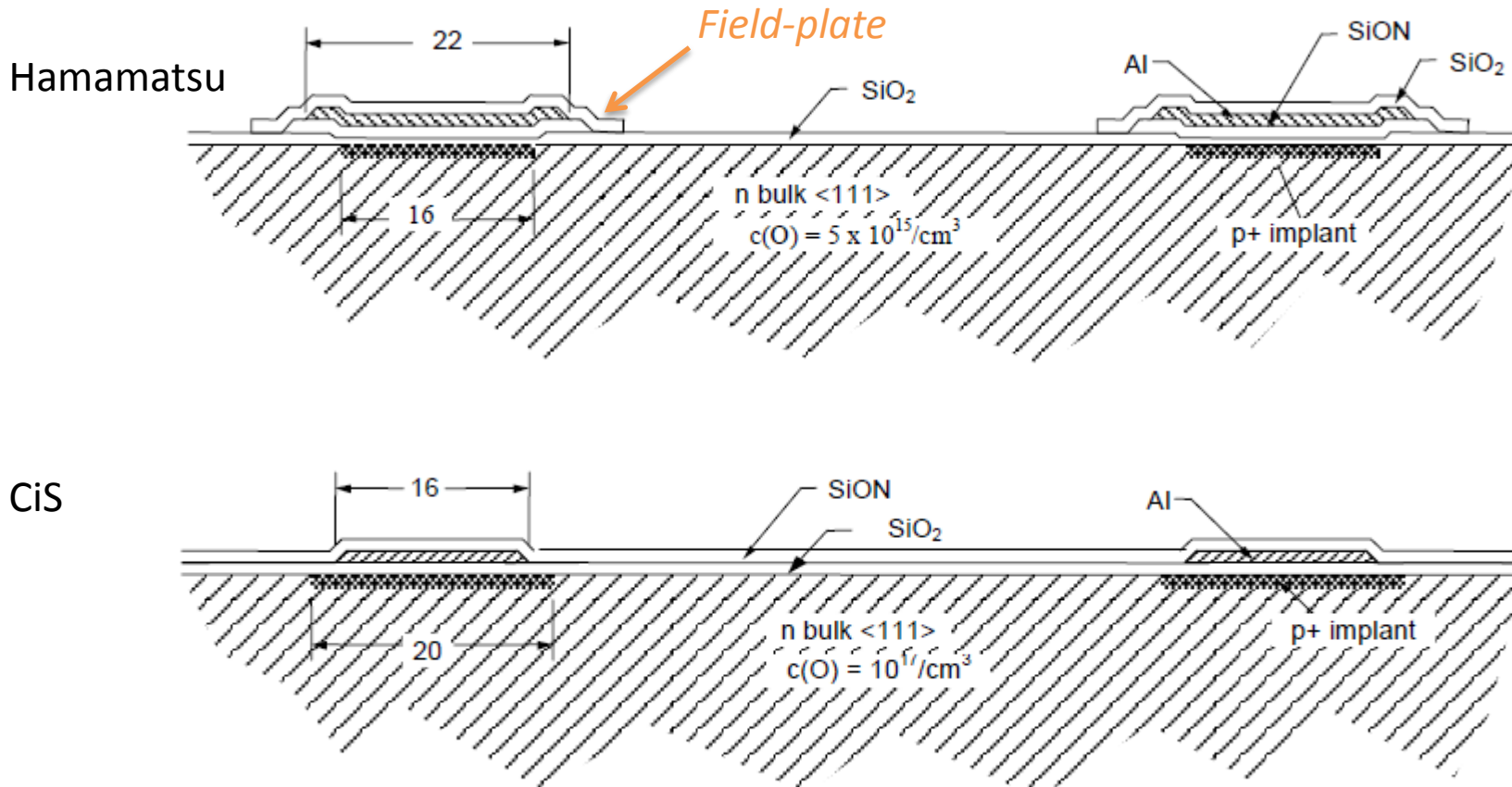
- model of signal digitisation in simulation
- radiation damage

✓ Measurements with cosmic ray and collision data both compatible with model predictions





# Why CiS (but not Hamamatsu)?

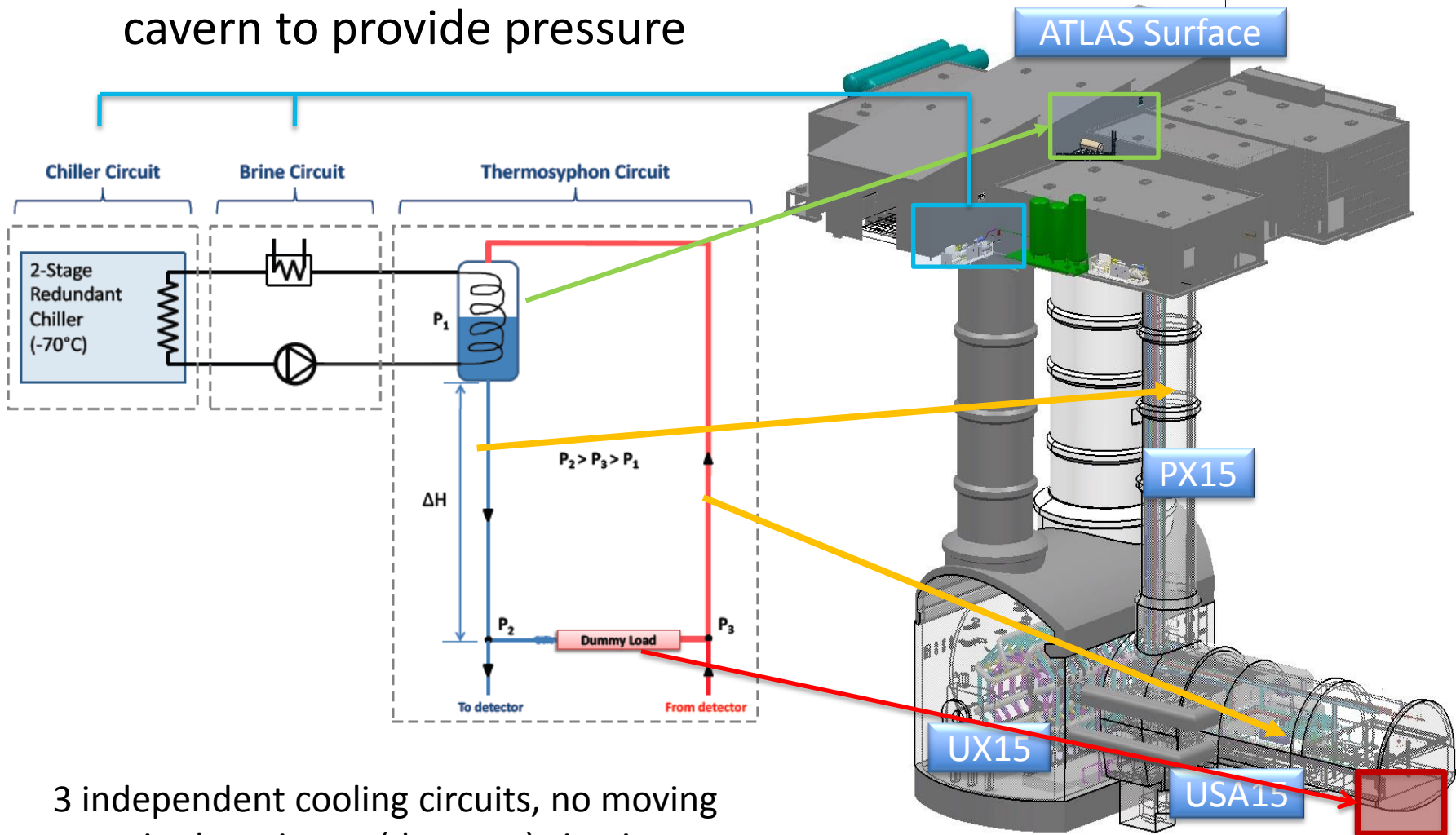


Origin of high noise and high current not fully understood, but CiS SCT sensors have known design and processing issues that impact on leakage current:

- Lack of field plate overlapping strip implants (field plates can suppress microdischarge)
- Resistive passivation leads to more surface charge migration

# The Thermosiphon Project

Replace the compressor system for cooling the SCT (and pixels) using 90m drop of  $C_3F_8$  feed from the surface to the cavern to provide pressure



3 independent cooling circuits, no moving parts in the primary (detector) circuit